

Material Content Data Sheet								
Sales Product Name	IM818-LCC			**Issued**		15. April 2021		
MA#	MA005412688							
Package	PG-MDIP-24-63			**Weight:**		6900.96 mg		
Construction Element	**Material group**	Materials	**CAS if applicable**	**Weight [mg]**	**Average mass [%]**	**Sum [%]**	**Average mass [ppm]**	**Sum [ppm]**
chip_01	inorganic material	silicon	7440-21-3	6.694	0.10	0.10	970	970
chip_02	inorganic material	silicon	7440-21-3	1.944	0.03	0.03	282	282
chip_03	inorganic material	silicon	7440-21-3	1.944	0.03	0.03	282	282
chip_04	inorganic material	silicon	7440-21-3	1.944	0.03	0.03	282	282
chip_05	inorganic material	silicon	7440-21-3	1.944	0.03	0.03	282	282
chip_06	inorganic material	silicon	7440-21-3	1.944	0.03	0.03	282	282
chip_07	inorganic material	silicon	7440-21-3	1.944	0.03	0.03	282	282
chip_08	inorganic material	silicon	7440-21-3	3.363	0.05	0.05	487	487
chip_09	inorganic material	silicon	7440-21-3	3.363	0.05	0.05	487	487
chip_10	inorganic material	silicon	7440-21-3	3.363	0.05	0.05	487	487
chip_11	inorganic material	silicon	7440-21-3	3.363	0.05	0.05	487	487
chip_12	inorganic material	silicon	7440-21-3	3.363	0.05	0.05	487	487
chip_13	inorganic material	silicon	7440-21-3	3.363	0.05	0.05	487	487
leadframe	inorganic material	phosphorus	7723-14-0	0.390	0.01		56	
	non noble metal	iron	7439-89-6	1.300	0.02		188	
	non noble metal	copper	7440-50-8	1298.097	18.81	18.84	188104	188348
wire	noble metal	gold	7440-57-5	0.758	0.01		110	
	non noble metal	aluminium	7429-90-5	33.170	0.48	0.49	4807	4917
encapsulation	organic material	carbon black	1333-86-4	30.682	0.44		4446	
	plastics	epoxy resin	-	383.527	5.56		55576	
	inorganic material	silicondioxide	60676-86-0	3421.063	49.58	55.58	495736	555758
leadfinish	non noble metal	tin	7440-31-5	41.697	0.60	0.60	6042	6042
plating	non noble metal	nickel	7440-02-0	2.741	0.04	0.04	397	397
solder	non noble metal	antimony	7440-36-0	1.815	0.03		263	
	noble metal	silver	7440-22-4	4.537	0.07		658	
	non noble metal	tin	7440-31-5	11.797	0.17	0.27	1710	2631
glue	inorganic material	silicondioxide	60676-86-0	0.084			12	
	plastics	epoxy resin	-	0.126			18	
	plastics	acrylic resin	-	0.249			36	
	plastics	maleimide resin	-	0.249			36	
	noble metal	silver	7440-22-4	0.746	0.01	0.01	108	210
smd	inorganic material	silicondioxide	60676-86-0	0.003			1	
	noble metal	gold	7440-57-5	0.012			2	
	noble metal	palladium	7440-05-3	0.019			3	
	noble metal	silver	7440-22-4	0.030			4	
	organic material	ethyl cellulose	9004-57-3	0.024			4	
	organic material	DEGBE	112-34-5	0.105			15	
	inorganic material	cobalt(II)oxide	1307-96-6	0.200			29	
	inorganic material	copperoxide	1317-38-0	0.576	0.01		83	
	inorganic material	manganesedioxide	1313-13-9	0.658	0.01	0.02	95	236
pcb metal	non noble metal	copper	7440-50-8	21.446	0.31	0.31	3108	3108
pcb plastic	plastics	epoxy resin	-	105.646	1.53		15309	
	inorganic material	glass fibre wool	65997-17-3	129.123	1.87	3.40	18711	34020
pcb plating	noble metal	gold	7440-57-5	0.066			10	
	non noble metal	nickel	7440-02-0	3.029	0.04	0.04	439	449
dcb ceramic	inorganic material	zirconium dioxide	1314-23-4	7.862	0.11		1139	
	inorganic material	aluminum nitride	24304-00-5	697.271	10.10	10.21	101040	102179

dcb metal	non noble metal	copper	7440-50-8	663.327	9.61	9.61	96121	96121
deviation	< 10%				Sum in total:	100.00		1000000

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